

PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Docket No: Q78432

Hien Boon TAN, et al.

Appln. No.: 10/721,382

Group Art Unit: 2822

Confirmation No.: 6007

Examiner: David E. Graybill

Filed: November 26, 2003

For: HIGH PERFORMANCE CHIP SCALE LEADFRAME PACKAGE METHOD OF
MANUFACTURING

RESPONSE TO NOTICE OF NON-COMPLIANT AMENDMENT

MAIL STOP AMENDMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

In response to the "Notice of Non-Compliant Amendment," mailed May 19, 2008,
submitted herewith is a corrected AMENDMENT TO THE CLAIMS section.

TABLE OF CONTENTS

AMENDMENTS TO THE CLAIMS2

REMARKS